

LEADED

BGA SOLDER PASTE

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Sn63/Pb37

Melting point 183°C



Product Usage

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TIN PASTE

Type number	BST-506B
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183°C
G.W.	20g
size	38*32mm



Sn63/Pb37

Melting point at medium temperature

183°C



Low residue



Solder spot bright

Rapid welding

Welding requirements for a wide range of products



**SMT
patch**



**LED
patch**



**BGA
welding**



Product List

G.W.:20g

